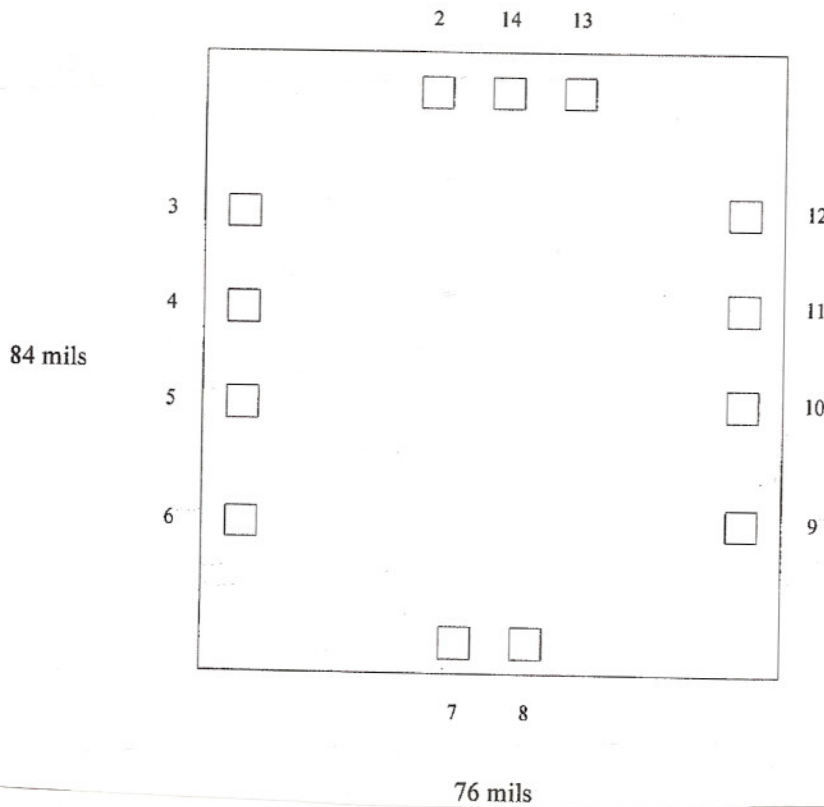




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



PAD FUNCTION

- 1 NC
- 2 S₃
- 3 D₃
- 4 D₁
- 5 S₁
- 6 A₁
- 7 GND
- 8 V-
- 9 A₂
- 10 S₂
- 11 D₂
- 12 D₄
- 13 S₄
- 14 V+

NC = NO CONNECT

Topside Metal: Al
Backside: Si
Backside Potential: Isolated
Mask Ref: 3847
Bond Pads (Mils): .004" x .004"

APPROVED BY:
MFG: Harris

DIE SIZE (Mils): .076" X .084"
THICKNESS: .019"

DATE: 6/9/04
P/N: HI-303-6